CLAIMS

1. Infrared blocking powder, which is produced by forming a mixture of an indium salt, an antimony salt, and a tin salt in a mixing ratio of 15 to 90 wt% : 1 to 20 wt% : 5 to 80 wt%, dissolving the mixture in water, adding a growth inhibitor and a basic solution into the water having the dissolved mixture to precipitate powder, rinsing the powder, drying the rinsed powder, and sintering the dried powder.

2. The infrared blocking powder as set forth in claim 1, wherein the indium salt, the antimony salt and the tin salt are indium nitrate ($In(NO_3)_3$), antimony chloride ($SbCl_3$) and tin chloride ($SnCl_2$), respectively.

3. The infrared blocking powder as set forth in claim 1, wherein the sintering of the dried powder is conducted at 400 to 1000℃ under an oxygen-free hydrogen atmosphere.

4. Infrared blocking solution, comprising:
the infrared blocking powder according to any one of claims 1 to 3, dispersed in a solvent, the solvent being selected from the group consisting of alcohol, water, an organic solvent, and a mixture thereof.

5. The infrared blocking solution as set forth in claim 4, wherein the infrared blocking powder has a particle size of 5 to 200 nm.

6. Infrared blocking solution, comprising:
the infrared blocking powder according to any one of claims 1 to 3;
solvent;
conductive polymer;
organic dispersion agent; and
photoinitiator.

7. The infrared blocking solution as set forth in claim 6, wherein the infrared blocking powder has a particle size of 5 to 200 nm.

8. The infrared blocking solution as set forth in claim 6, wherein a content of the infrared blocking powder is 5 to 70 wt% in the infrared blocking solution.

9. Infrared blocking material, which is produced by coating the infrared blocking solution according to claim 6 on a surface of a base.

10. The infrared blocking material as set forth in claim 9, wherein an adhesive layer is formed on any one side of the infrared blocking material coated on the base.